

Page 2
Block Diagram

Page 3
Connector, Hot Swap & EEPROM

Page 4
Isolated Power, Digital Isolators & LDOs

Page 5
Thermocouple & RTD

Page 6
Pressure Sensor

Page 7
Delta-Sigma & MUX

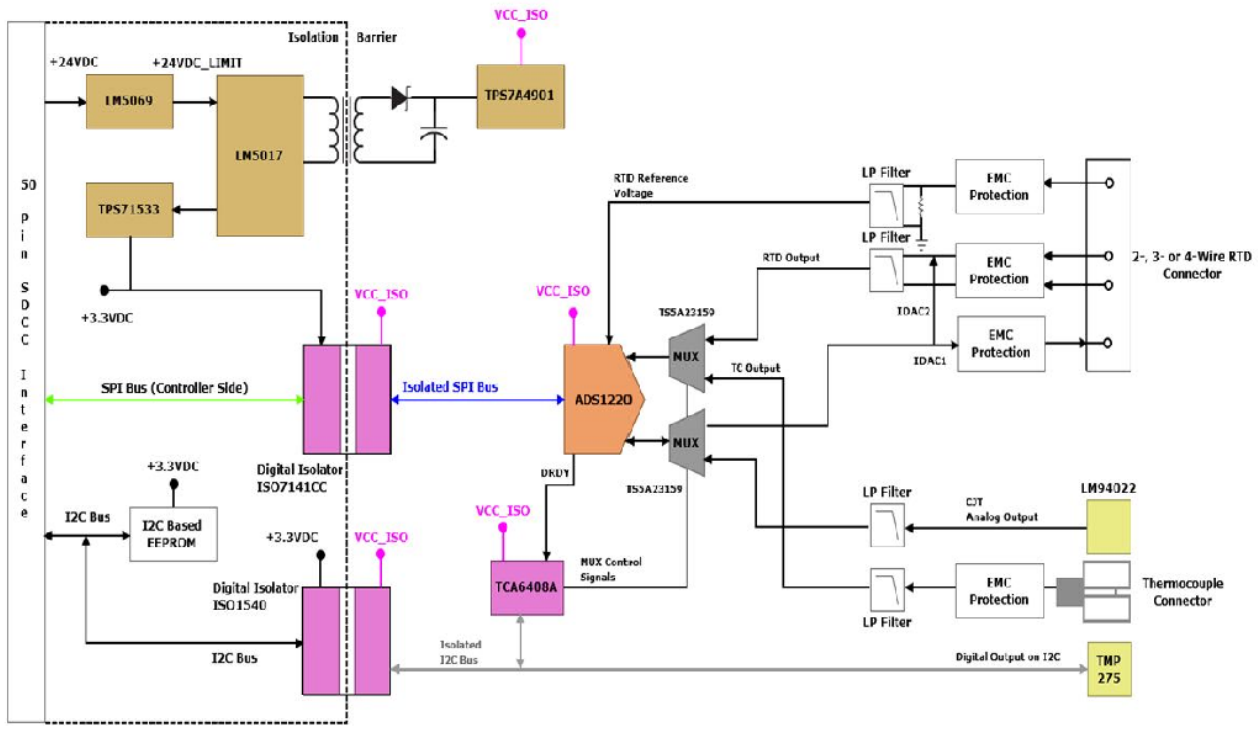
Page 8
Mechanical Parts and Logo

Revision History	
Revision	Notes

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Number: TIDA-00018	Rev: E1	Designed for: PUBLIC Release	Mod Date: 3/24/2014
SVN Rev.: Not in version control		Project Title: Temperature Sensor Interface Module for PLC	
Drawn By:		Assembly Variant: 001	Sheet: 1 of 8
Engineer: Sharad Yadav	File: Sheet-1 Index Page.SchDoc		Size: B
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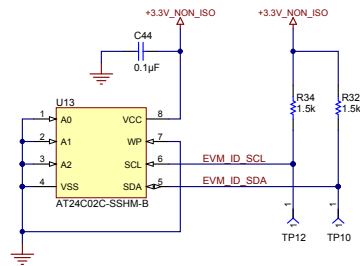
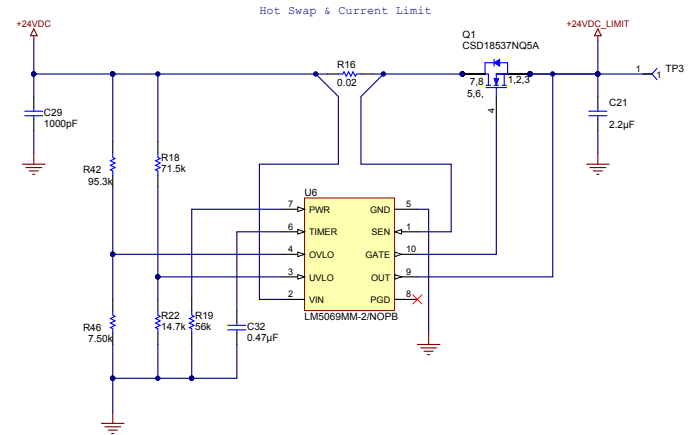
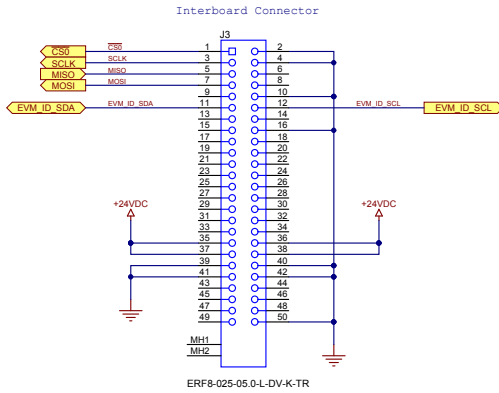
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SVN Rev.: Not in version control		Project Title: Temperature Sensor Interface Module for PLC	
Drawn By:	Engineer: Sharad Yadav	Assembly Variant: 001	Sheet: 2 of 8
File: Sheet-2 Block Diagram.SchDoc		Size: B	
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50
pin
SDCC
Interface

2-, 3- or 4-Wire RTD Connector

Thermocouple Connector



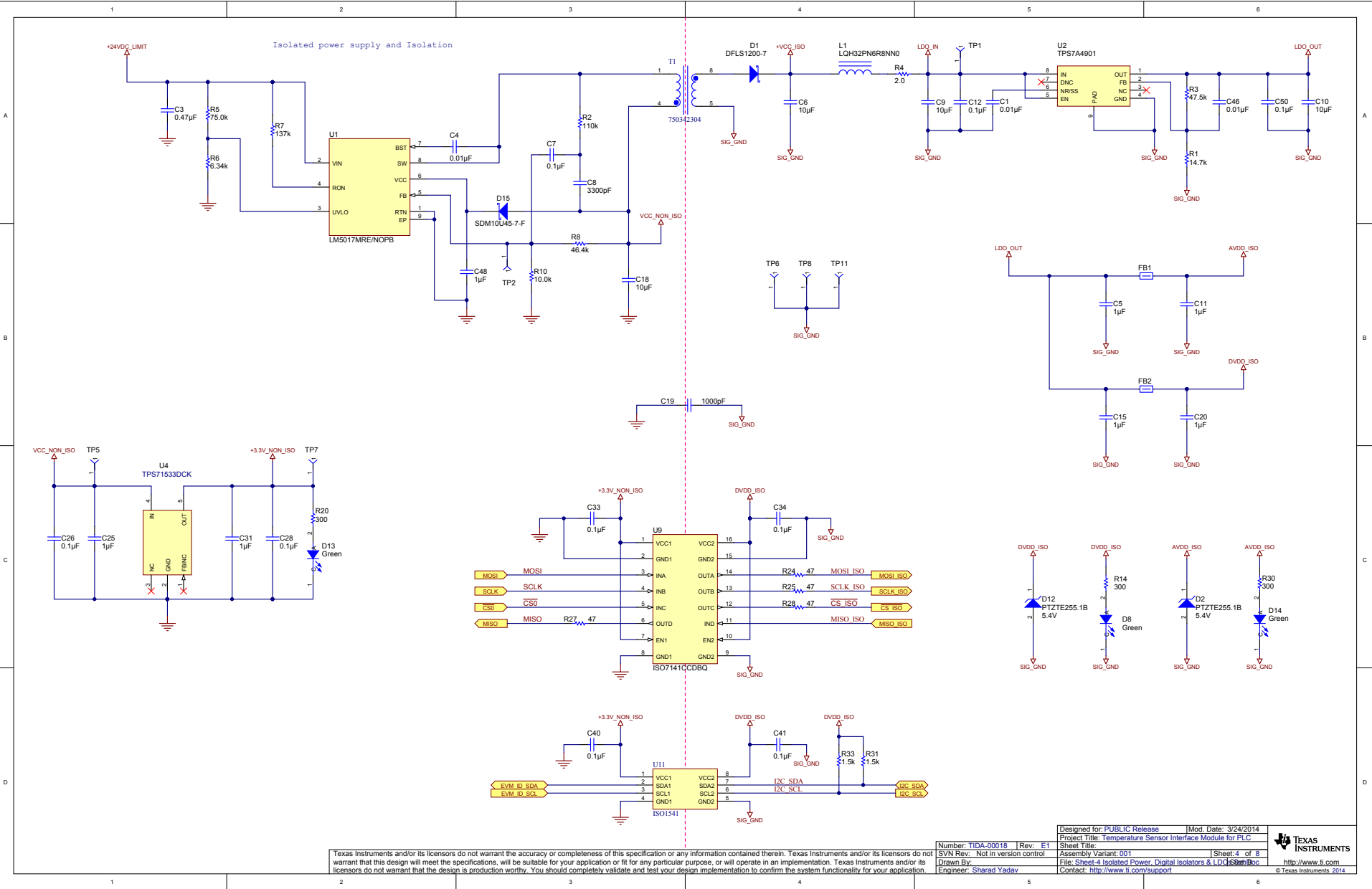
EEPROM: Board ID & Calibration Data

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SVM Rev.: Not in version control		Project Title: Temperature Sensor Interface Module for PLC	
Drawn By:		Assembly Variant: 001	Sheet: 3 of 8
Engineer: Sharad Yadav	Contact: http://www.ti.com/support	File: Sheet-3 Connector, Hot Swao & EEPROM.Sch	Size: B



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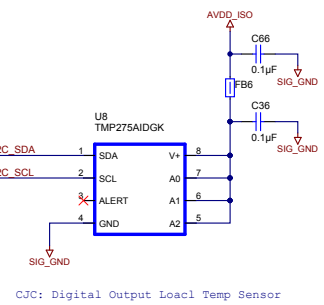
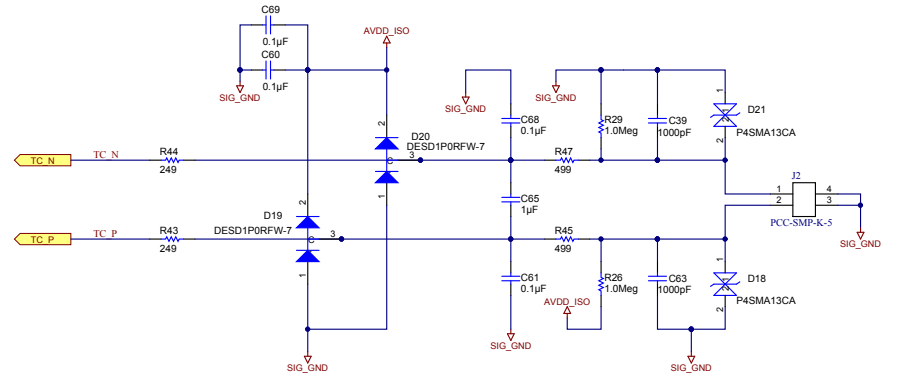
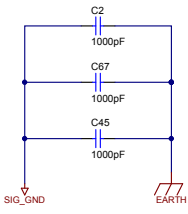
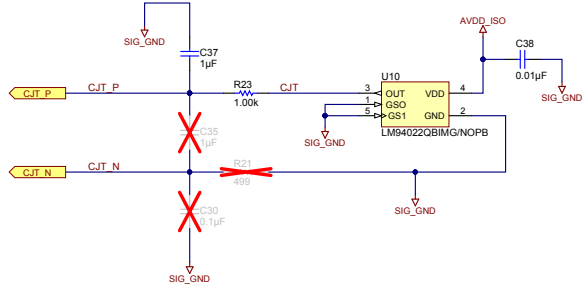
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SVN Rev.: Not in version control		Project Title: Temperature Sensor Interface Module for PLC	
Drawn By:		Sheet Title:	
Engineer: Sharad Yadav		Assembly Variant: 001	
		File: Sheet-4 Isolated Power, Digital Isolators & LDOs.mxd	
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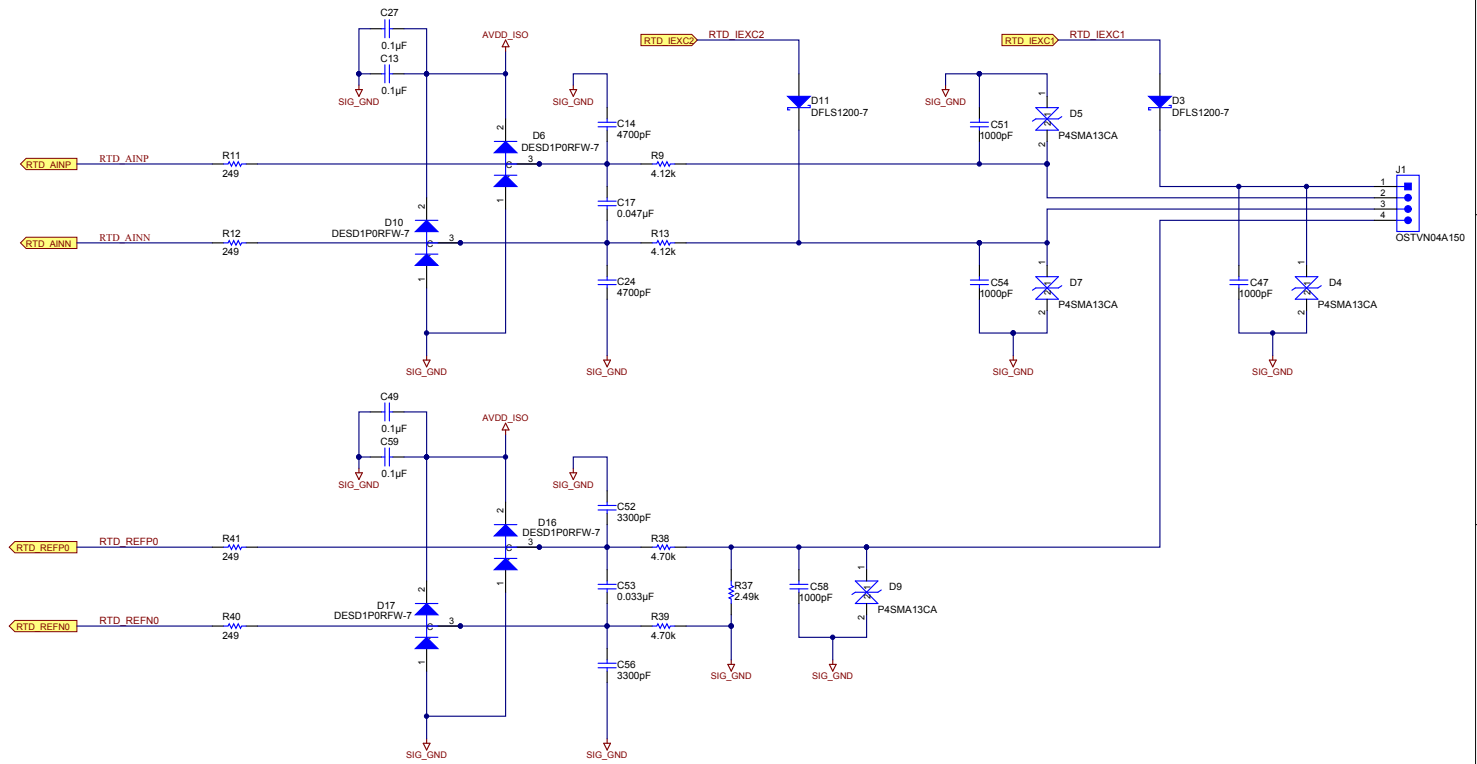


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CJC: Analog Output Load Temp Sensor



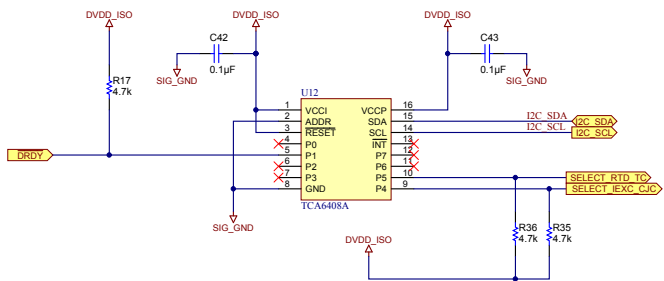
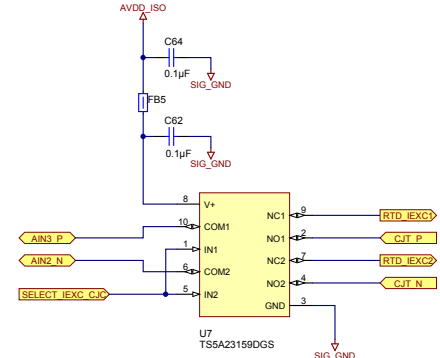
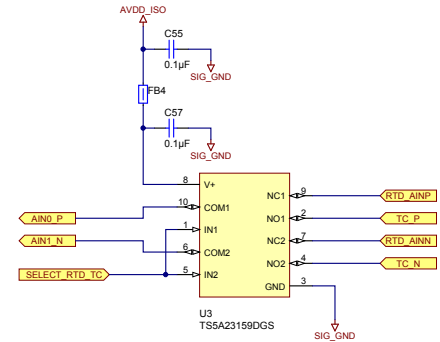
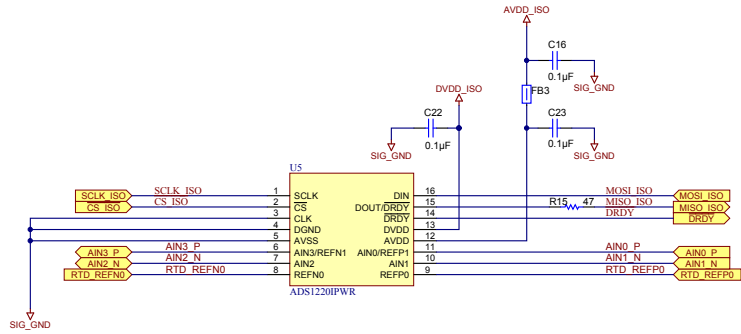
CJC: Digital Output Load Temp Sensor



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Project Title: Temperature Sensor Interface Module for PLC			
Sheet Title:			
Number: TIDA-00018		Rev: E1	
SVN Rev.: Not in version control		Assembly Variant: 001	
Drawn By:		File: Sheet-5 RTD_SchDoc	
Engineer: Sharad Yadav		Contact: http://www.ti.com/support	
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		Size: B	
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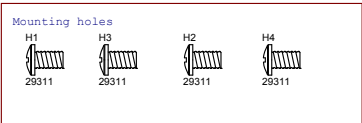




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Drawn By: Engineer: Sharad Yadav		Sheet Title: Assembly Variant: 001	
File: Sheet7 Delta-Sigma & MUX.SchDoc		Sheet: 7 of 8	
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PCB Number: TIDA-00018
PCB Rev: PCB_Rev

PCB
LOGO
Texas Instruments

LBL1
PCB Label
Size: 0.65" x 0.20"

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